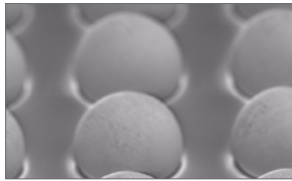
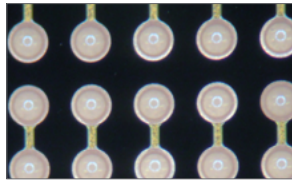
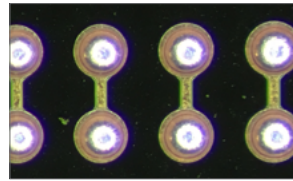
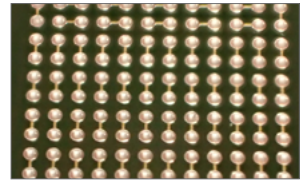


ALPHA[®] Flux Paste

Flux Pastes for WL CSP / FO WLP, CSP and BGA Semiconductor Packaging

DESIGNED FOR BALL ATTACH, LAB, MR AND TCB FLIP CHIP PROCESSING FOR BOTH SAC AND LTS ALLOYS

- High Tack with Excellent print and pin transfer consistency for HVM process capability across multiple packages and wafer designs
- Halide and Halogen free materials
- Excellent wetting and solderability with minimum voiding on various finishes (Cu, CuOSP, NiAu)
- Low temperature, easy to remove WS flux residues in standard DI washing (< 40 C)
- High Reliability Epoxy flux residues able to pass IPC SIR and Electromigration requirements



FLUX PASTE PRODUCT LINE

Product Name	Material Type	Deposition Method			Properties				Component Type
		Pin Transfer	Print	Dip	Halide Free	Activity	Viscosity	Tackiness	
NCX340	No Clean	o	o	o		Hi	Med	Hi	BGA/FCCSP
NCX-390		o		o	o	Hi	Med	Hi	BGA/FCCSP
NCX402-M3				o	o	Hi	Med	Hi	BGA/FCCSP
NCX PRL-507	Epoxy		o			Lo	Hi	Hi	Wafer
WS608	Water Soluble	o	o	o	o	Hi	Hi	Hi	BGA/FCCSP
WS600-MHV		o	o	o	o	Hi	Hi	Hi	BGA/wafer
WS698		o	o	o	o	Hi	Hi	Hi	BGA/FCCSP
WS9180-MHV		o	o	o	o	Hi	Hi	Hi	BGA/wafer
WSX-HF-HAHV		o	o	o	o	Hi	Hi	Hi	BGA/wafer
WS9160-M7		o	o	o	o	Hi	Med	Hi	BGA/wafer
WSX-9200		o	o	o	o	Hi	Hi	Hi	BGA/FCCSP
WS-630		o	o	o	o	Hi	Hi	Hi	BGA/FCCSP
WSX9284		o	o	o	o	Hi	Hi	Hi	BGA/FCCSP



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